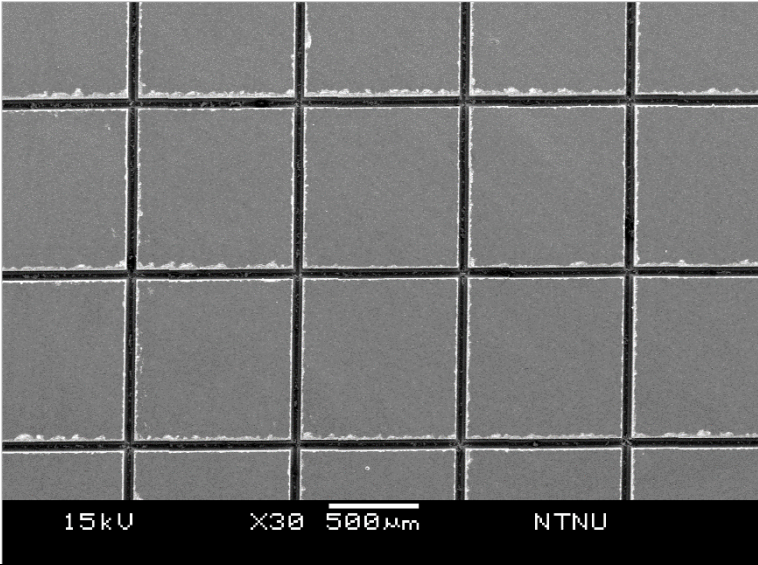
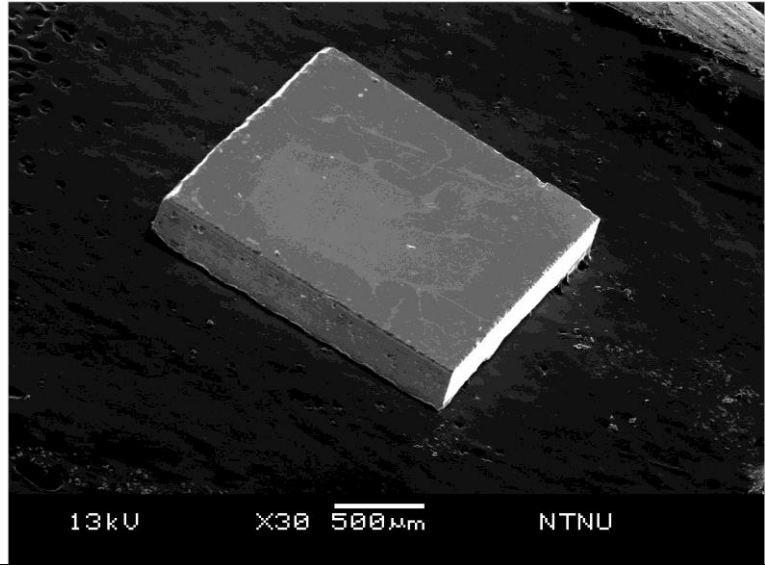


2019 具線上放電銳化技術之晶粒分割系統開發與矽晶圓基板晶粒分割研究	
Graduate student : Chun-Hung Hu	
	
Product	<i>Die Separation Groove Array on Silicon Wafer (10×10 Array with 1 mm in Pitch)</i>
Material	<i>Silicon Wafer</i>
Tool	<i>Boron-doped Polycrystalline Composite Diamond Wheel</i>
Groove width	<i>60 µm</i>
Approach	<i>In-situ w-EDD, Brittle-like grinding regime, Intellectualized grinding-force feedback</i>
Application	<i>Semiconductor industry</i>
Technical Description	<i>By applying the mechanism of intellectualized grinding force feedback and the dressed BD-PCD wheel tool with 30 µm thickness, a die separation with an array of 10×10 on silicon wafer substrate is verified.</i>

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Product	<i>Silicon Die</i>
Material	<i>Silicon Wafer</i>
Tool	<i>Boron-doped Polycrystalline Composite Diamond Wheel</i>
Die Size	<i>2 mm x 2 mm</i>
Approach	<i>In-situ w-EDD, Brittle-like grinding regime, Intellectualized grinding-force feedback</i>
Application	<i>Semiconductor industry</i>
Technical Description	<i>By a die separation with intellectualized grinding force feedback and the dressed BD-PCD wheel tool with 30 µm thickness, a 2 mm x 2 mm die on silicon wafer substrate is verified.</i>

